ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	ckburn, Illinois, A	ll rights reserved untions.	, inder both	This docume level parts, th	ent is a declara he declaration	ion of the succession of the s	ubstances s all lowe	within the materia	anufacturer als for whic	listed item. N ch the manufa	ote: if the	e item is an ass s engineering r	embly with lowe esponsibility.
21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Inf					s and Mfg Info	ormation		
Supplier Information													
Company name* Company unique ID				Unique ID Authority					ŀ	Response Date*			
semi										2025-06-08			
Contact Name	Title - Contact			1	Phone - Contact*				F	Email - Contact*			
Product-Env-Stewards	wards Product Enviro Compliance			NA					1	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative				Phone - Representative*					F	Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA				1	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr I	Mfr Item Number		Mfr Item Name		Effective Date	e Version]	Manufacturing Site		Weigh	t*	UOM	Unit Type
SBC	47BPDXV6T1G SS SOT563 GP XST		STR PNP 40V		2025-06-08	CN1		CN1		2.72		mg	Each
Manufacturing Proccess Information		·			·					·			
Terminal Plating / Grid Array Material	Terminal Base Alloy J-STD-020			Rating	Peak Pro	Peak Process Body Temperature Max Time at Pe		e at Peak Te	Temperature Number of Reflow Cycles		es		
Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30		seconds	3			
omments													
vel 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds											
or more information regarding material compositi	on please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg	
Lead Frame 1	1.18	mg	В	Nickel (Ni)	7440-02-0		0.4779	mg	
			Supplier	Iron (Fe)	7439-89-6		0.6549	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0472	mg	
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg	
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg	
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg	